



DFN4L-8*8 物料成分表

Material Composition Data

构成部件 Sub-part(if yes)		构成成分 Composition		CAS编号 CAS No.	化学成分%
英文名称 English	重量(mg) Weight	英文名称 English			
Die	14.07	Si	7440-21-3	100.00%	
Lead Frame	65.79	Fe	7440-21-3	10.00%	
		P	7723-14-0	3.25%	
		Pb	7439-92-1	0.25%	
		Cu	7440-50-8	86.50%	
Solder	7.39	Pb	7439-92-1	80.00%	
		Sn	7440-31-5	7.00%	
		Ag	7440-22-4	3.00%	
		混合醚	-	4.50%	
		氢化松香	65997-06-0	4.50%	
		Others	-	1.00%	
Wire	1.15	Cu	7429-90-5	99.99%	
		Others	7429-90-5	0.01%	
Mold Compound	109	Silica, vitreous	60676-86-0	82.50%	
		Silicon dioxide	7631-86-9	4.00%	
		Phenol polymer with ar, ar'-bis(methoxymethyl)-1,1'-	223769-10-6	4.00%	
		Mixture of 1,1'-[1-[4-[1-[4-(2,3-epoxypropoxy)phenyl]-1-	115254-47-2	3.00%	
		Phenol polymer with 4,4'-bis(methoxymethyl)1,1'-	205830-20-2	3.00%	
		1,3-Benzenediol polymer with 4,4'-bis(chloromethyl)-1,1'-	918825-38-4	3.00%	
		Carbon black	1333-86-4	0.5000%	
Plating	2.6	Tin	7440-31-5	≥99.99%	
Total	200				

Notes: Lead in internal soft solder, ROHS exemption clause Annex 7a"lead in high melting temperature type solders" applied. Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, it is for guidance only and we cannot guarantee to its accuracy or completeness.